



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No.: 09/296,928

Group Art Unit: 2877

Filed: April 22, 1999

Examiner: Pham, H. #9/B

For: Chemical Mechanical Planarization
(CMP) Slurry Quality Control Process
And Particle Size Distribution Measuring
Systems

Docket No.: 7009/018CP

marsha
1/9/01

Inventors: Cerni et al.

Certificate of Mailing Under 37 CFR 1.8

I hereby certify that this correspondence, along with all papers referred to as being enclosed or attached, are being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to Commissioner for Patents, Washington, DC 20231.

December 29, 2000

Date

Elaine C. VonSpreckelsen

Elaine C. VonSpreckelsen

COMMISSIONER FOR PATENTS
WASHINGTON, DC 20231

Sir:

This Amendment and Remarks is responsive to the Office Action mailed September 26, 2000.

AMENDMENT

Please amend claims 1 and 26 as follows:

1. (Amended) A quality control process for detecting physical and/or chemical changes in a CMP slurry, comprising the steps of:

transmitting radiation through a flow of [the CMP] ^{an undiluted optically dense} slurry as used in a chemical mechanical planarization (CMP) process, the radiation having one or more [wavelengths] wavelengths;

determining transmission of the transmitted radiation at each of the wavelengths;
and

monitoring transmission, over time, to detect physical and/or chemical changes of

Serial No. 09/296,928

Amendment and Remarks Responsive to
Office Action Mailed 9/26/00

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